DSC-WX300

SERVICE MANUAL

LEVEL 3

Ver. 1.0 2013.03

Photo: Black

US Model
Canadian Model
AEP Model
UK Model
Russian Model
E Model
Australian Model
Hong Kong Model
Chinese Model
Korea Model
Japanese Model
Tourist Model

Check the SERVICE NOTE (LEVEL 2) before the service.

DIGITAL STILL CAMERA

SONY®

The components identified by mark ⚠ or dotted line with mark ⚠ are critical for safety. Replace only with part number specified.	Les composants identifiés par une marque ⚠ sont critiques pour la sécurité. Ne les remplacer que par une pièce portant le numéro spécifié.

DSC-WX300_L3
9-834-730-11

Revision History

Ver.	Date	History	Contents	S.M. Rev. issued
1.0	2013.03	Official Release	—	—

Sony Corporation

2013C08-1

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Caution
Danger of explosion if battery is incorrectly replaced. Replace only with the same or equivalent type. Dispose of used batteries according to the instructions.

SAFETY-RELATED COMPONENT WARNING!!

COMPONENTS IDENTIFIED BY MARK ⚠ OR DOTTED LINE WITH MARK ⚠ ON THE SCHEMATIC DIAGRAMS AND IN THE PARTS LIST ARE CRITICAL TO SAFE OPERATION. REPLACE THESE COMPONENTS WITH SONY PARTS WHOSE PART NUMBERS APPEAR AS SHOWN IN THIS MANUAL OR IN SUPPLEMENTS PUBLISHED BY SONY.

ATTENTION AU COMPOSANT AYANT RAPPORT À LA SÉCURITÉ!

LES COMPOSANTS IDENTIFIÉS PAR UNE MARQUE ⚠ SUR LES DIAGRAMMES SCHÉMATIQUES ET LA LISTE DES PIÈCES SONT CRITIQUES POUR LA SÉCURITÉ DE FONCTIONNEMENT. NE REMPLACER CES COMPOSANTS QUE PAR DES PIÈCES SONY DONT LES NUMÉROS SONT DONNÉS DANS CE MANUEL OU DANS LES SUPPLÉMENTS PUBLIÉS PAR SONY.

SAFETY CHECK-OUT

After correcting the original service problem, perform the following safety checks before releasing the set to the customer.

1. Check the area of your repair for unsoldered or poorly-soldered connections. Check the entire board surface for solder splashes and bridges.
2. Check the interboard wiring to ensure that no wires are “pinched” or contact high-wattage resistors.
3. Look for unauthorized replacement parts, particularly transistors, that were installed during a previous repair. Point them out to the customer and recommend their replacement.
4. Look for parts which, through functioning, show obvious signs of deterioration. Point them out to the customer and recommend their replacement.
5. Check the B+ voltage to see it is at the values specified.
6. Flexible Circuit Board Repairing
   - Set the soldering iron tip temperature to 350 °C approximately.
   - Do not touch the soldering iron on the same conductor of the circuit board (within 3 times).
   - Be careful not to apply force on the conductor when soldering or unsoldering.

UNLEADED SOLDER

This unit uses unleaded solder.
Boards requiring use of unleaded solder are printed with the lead free mark (LF) indicating the solder contains no lead.
(**Caution:** Some printed circuit boards may not come printed with the lead free mark due to their particular size.)

LF : LEAD FREE MARK
Be careful to the following points to solder or unsolder.

- Set the soldering iron tip temperature to 350 °C approximately.
  If cannot control temperature, solder/unsolder at high temperature for a short time.
  Caution: The printed pattern (copper foil) may peel away if the heated tip is applied for too long, so be careful!
  Unleaded solder is more viscous (sticky, less prone to flow) than ordinary solder so use caution not to let solder bridges occur such as on IC pins, etc.
- Be sure to control soldering iron tips used for unleaded solder and those for leaded solder so they are managed separately. Mixing unleaded solder and leaded solder will cause detachment phenomenon.

注意
電池の交換は，正しく行わないと破裂する恐れがあります。 電池を交換する場合には必ず同じ型名の電池又は同等品と交換してください。 使用済み電池は，取扱指示に従って処分してください。

サービス，点検時には次のことにご注意ください。

1. 注意事項をお守りください。
   サービスのとき特に注意を要する個所については，キャビネット，シャーシ，部品などにラベルや捺印で注意事項を表示しています。これらの注意書き及び取扱説明書等の注意事項を必ずお守り下さい。
2. 指定部品のご使用を
   セットの部品は難燃性や耐電圧など安全上の特性を持ったものとなっています。従って交換部品は，使用されていたものと同じ特性の部品を使用して下さい。特に回路図，部品表に⚠印で指定されている安全上重要な部品は必ず指定のものをご使用下さい。
3. 部品の取付けや配線の引きまわしはもとどおりに
   安全上，チューブやテープなどの絶縁材料を使用したり，プリント基板から浮かして取付けた部品があります。また内部配線は引きまわしやクランパによって発熱部品や高圧部品に接近しないよう配慮されていますので，これらは必ずもとどおりにして下さい。
4. サービス後は安全点検を
   サービスのために取外したネジ，部品，配線がもとどおりになっているか，またサービスした個所の周辺を劣化させてしまったところがないかなどを点検し，安全性が確保されていることを確認して下さい。
5. チップ部品交換時の注意
   - 取外した部品は再使用しないで下さい。
   - タンタルコンデンサのマイナス側は熱に弱いため交換時は注意して下さい。
6. フレキシブルプリント基板の取扱いについて
   - 半田こてのこて先温度は約350℃に設定してください。
   - 同一パターンに何度もコテ先を当てないで下さい。（3回以内）
   - パターンに力が加わらないよう注意して下さい。

無鉛半田について
本機には無鉛半田が使用されています。
無鉛半田を使用している基板には，無鉛(Lead Free)を意味するレッドフリーマークがプリントされています。
(注意：基板サイズによっては，無鉛半田を使用していてもレッドフリーマークがプリントされていないものがあります)

LF：レッドフリーマーク
無鉛半田は，下記の点に注意して使用してください。

- 半田こてのこて先温度は約350℃に設定してください。
  温度調節が無理な場合は，高温短時間で作業を行ってください。
  注意：半田こてを長く当てすぎると，基板のパターン(銅箔)がはがれてしまうことがありますので，注意してください。また，従来の半田よりも粘性が強いため，IC端子などが半田ブリッジしないように注意してください。
- 半田こてのこて先は，必ず無鉛半田用と有鉛半田用に分けて管理してください。
  無鉛半田と有鉛半田が混在すると剥離現象が発生してしまいます。

(ENGLISH)

NOTE:

- -XX, -X mean standardized parts, so they may have some differences from the original one.
- Items marked "*" are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- The mechanical parts with no reference number in the exploded views are not supplied.
- Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.
- CAPACITORS:
  uF: μF
- COILS
  uH: μH
- RESISTORS
  All resistors are in ohms.
  METAL: metal-film resistor
  METAL OXIDE: Metal Oxide-film resistor
  F: nonflammable
- SEMICONDUCTORS
  In each case, u: μ, for example:
  uA...: μA... , uPA... , μPA... ,
  uPB... , μPB... , uPC... , μPC... ,
  uPD..., μPD...

When indicating parts by reference number, please include the board name.

The components identified by mark ⚠ or dotted line with mark ⚠ are critical for safety.
Replace only with part number specified.

Les composants identifiés par une marque ⚠ sont critiques pour la sécurité.
Ne les remplacer que par une pièce portant le numéro spécifié.

Caution
Danger of explosion if battery is incorrectly replaced.
Replace only with the same or equivalent type.
Dispose of used batteries according to the instructions.

Note : Be sure to read "Precautions for Replacement of Imager" on page 6-1.

(JAPANESE)

【使用上の注意】

- ここに記載されている部品は，補修用部品であるため，回路図及びセットに付いている部品と異なる場合があります。
- -XX, -Xは標準化部品のため，セットに付いている部品と異なる場合があります。
- *印の部品は常備在庫しておりません。
- コンデンサの単位でuFはμFを示します。
- 抵抗の単位Ωは省略してあります。
  金　　被：金属被膜抵抗。
  サンキン：酸化金属被膜抵抗。
- インダクタの単位でuHはμHを示します。
- 半導体の名称でuA..., uPA..., uPB..., uPC..., uPD...等はそれぞれμA..., μPA..., μPB..., μPC..., μPD...を示します。

お願い
図面番号で部品を指定するときは基板名又はブロックを併せて指定してください。

⚠印の部品，または⚠印付の点線で囲まれた部品は，安全性を維持するために，重要な部品です。
従って交換時は，必ず指定の部品を使用してください。

注意
電池の交換は，正しく行わないと破裂する恐れがあります。
電池を交換する場合には必ず同じ型名の電池又は同等品と交換してください。
使用済み電池は，取扱指示に従って処分してください。

Note : イメージャの交換時は6-1ページの"イメージャ交換時の注意"を必ずお読みください。

2-2. ELECTRICAL PARTS LIST

	Ref. No.	Part No.	Description			
		A-1933-256-A	CD-1004 FLEXIBLE BOARD, COMPLETE			
			********************************			

(All mount parts are not supplied, but they are included in CD-1004 FLEXIBLE COMPLETE BOARD.)

	Ref. No.	Part No.	Description			
		A-1933-117-A	ST-1009 FLEXIBLE BOARD, COMPLETE			
			*******************************			

(All mount parts are not supplied, but they are included in ST-1009 FLEXIBLE COMPLETE BOARD.)
(BT900 is not included in ST-1009 FLEXIBLE COMPLETE BOARD.)

< BATTERY >

	Ref. No.	Part No.	Description			
⚠	BT900	1-756-813-11	LITHIUM RECHARGEABLE BATTERY			

	Ref. No.	Part No.	Description			
		A-1939-392-A	SY-1015 BOARD, COMPLETE (SERVICE)			
			*******************************			

(C009, C010, C011, C014, C109, C110, C111, C115, C356, C365, C367, C372, C720, CN705, CN706, CP501, D002, IC001, IC003, IC051, IC211, IC503, L002, L003, L005, L006, R292 and TB501 are not supplied, but they are included in SY-1015 COMPLETE BOARD (SERVICE).)

< BATTERY TERMINAL >

	Ref. No.	Part No.	Description			
⚠	BH701	1-780-936-11	TERMINAL BOARD, BATTERY			

< CAPACITOR >

	Ref. No.	Part No.	Description			
*	C001	1-116-714-11	CERAMIC CHIP	22uF	20%	6.3V
*	C003	1-116-714-11	CERAMIC CHIP	22uF	20%	6.3V
	C004	1-116-717-11	CERAMIC CHIP	10uF	20%	10V
*	C005	1-116-714-11	CERAMIC CHIP	22uF	20%	6.3V
*	C006	1-116-714-11	CERAMIC CHIP	22uF	20%	6.3V
	C007	1-116-734-11	CERAMIC CHIP	1uF	20%	16V
	C009	(Not supplied)	CERAMIC CHIP	0.1uF	10%	16V
	C010	(Not supplied)	CERAMIC CHIP	0.1uF	10%	16V
	C011	(Not supplied)	CERAMIC CHIP	0.1uF	10%	16V
*	C012	1-116-714-11	CERAMIC CHIP	22uF	20%	6.3V
*	C013	1-116-714-11	CERAMIC CHIP	22uF	20%	6.3V
	C014	(Not supplied)	CERAMIC CHIP	1uF	10%	25V
	C015	1-116-717-11	CERAMIC CHIP	10uF	20%	10V
*	C017	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
*	C018	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
*	C019	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
*	C022	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
	C023	1-116-737-11	CERAMIC CHIP	1uF	20%	10V
*	C025	1-116-714-11	CERAMIC CHIP	22uF	20%	6.3V
*	C051	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
	C052	1-116-737-11	CERAMIC CHIP	1uF	20%	10V
	C053	1-116-720-11	CERAMIC CHIP	10uF	20%	6.3V
*	C055	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
	C056	1-116-720-11	CERAMIC CHIP	10uF	20%	6.3V
*	C104	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
*	C105	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
*	C106	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
	C109	(Not supplied)	CERAMIC CHIP	0.1uF	10%	16V
	C110	(Not supplied)	CERAMIC CHIP	0.1uF	10%	16V
	C111	(Not supplied)	CERAMIC CHIP	0.1uF	10%	16V
*	C114	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
	C115	(Not supplied)	CERAMIC CHIP	0.1uF	10%	16V

	Ref. No.	Part No.	Description			
	C116	1-128-605-11	CERAMIC CHIP	12PF	5%	25V
	C117	1-128-605-11	CERAMIC CHIP	12PF	5%	25V
	C118	1-116-724-11	CERAMIC CHIP	4.7uF	20%	6.3V
	C201	1-116-729-11	CERAMIC CHIP	2.2uF	20%	10V
	C203	1-116-729-11	CERAMIC CHIP	2.2uF	20%	10V
	C204	1-116-729-11	CERAMIC CHIP	2.2uF	20%	10V
*	C205	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C206	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C208	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
	C214	1-116-729-11	CERAMIC CHIP	2.2uF	20%	10V
*	C216	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C225	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C228	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C230	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
	C231	1-128-613-91	CERAMIC CHIP	47PF	5%	25V
*	C233	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
	C234	1-116-724-11	CERAMIC CHIP	4.7uF	20%	6.3V
*	C251	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C252	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C253	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C254	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C255	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C259	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C261	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C263	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C264	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C265	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C266	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C267	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C269	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
	C352	1-116-729-11	CERAMIC CHIP	2.2uF	20%	10V
	C356	(Not supplied)	CERAMIC CHIP	1uF	10%	25V
*	C357	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
	C358	1-100-743-91	CERAMIC CHIP	2.2uF	20%	16V
*	C359	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C360	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C361	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
	C365	(Not supplied)	CERAMIC CHIP	0.001uF	10%	25V
*	C366	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
	C367	(Not supplied)	CERAMIC CHIP	0.001uF	10%	25V
	C368	1-116-729-11	CERAMIC CHIP	2.2uF	20%	10V
*	C369	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C370	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C371	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
	C372	(Not supplied)	CERAMIC CHIP	0.001uF	10%	25V
	C373	1-116-729-11	CERAMIC CHIP	2.2uF	20%	10V
*	C431	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
*	C433	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C434	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C435	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C436	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
*	C441	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
	C456	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V
	C457	1-118-029-11	CERAMIC CHIP	0.0022uF	10%	16V
	C458	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V
*	C459	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
	C461	1-118-029-11	CERAMIC CHIP	0.0022uF	10%	16V
*	C462	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V

Ref. No.	Part No.	Description			
* C463	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
* C467	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
* C468	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
C470	1-128-632-91	CERAMIC CHIP	0.01uF	10%	6.3V
C471	1-128-632-91	CERAMIC CHIP	0.01uF	10%	6.3V
C472	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V
C473	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V
C474	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V
C475	1-100-965-91	CERAMIC CHIP	0.047uF	10%	6.3V
* C485	1-116-714-11	CERAMIC CHIP	22uF	20%	6.3V
C490	1-118-403-11	CERAMIC CHIP	0.001uF	10%	50V
C491	1-118-403-11	CERAMIC CHIP	0.001uF	10%	50V
C492	1-118-403-11	CERAMIC CHIP	0.001uF	10%	50V
C497	1-164-939-11	CERAMIC CHIP	0.0022uF	10%	50V
C498	1-164-939-11	CERAMIC CHIP	0.0022uF	10%	50V
C505	1-116-732-11	CERAMIC CHIP	2.2uF	20%	6.3V
C506	1-116-732-11	CERAMIC CHIP	2.2uF	20%	6.3V
C507	1-116-732-11	CERAMIC CHIP	2.2uF	20%	6.3V
C508	1-116-732-11	CERAMIC CHIP	2.2uF	20%	6.3V
C509	1-116-732-11	CERAMIC CHIP	2.2uF	20%	6.3V
* C511	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
* C706	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
* C708	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
* C712	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
* C713	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
* C715	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
C716	1-114-983-91	CERAMIC CHIP	2.2uF	10%	16V
C717	1-114-983-91	CERAMIC CHIP	2.2uF	10%	16V
* C718	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
C719	1-114-983-91	CERAMIC CHIP	2.2uF	10%	16V
C720	(Not supplied)	CERAMIC CHIP	1uF	10%	25V
C721	1-116-734-11	CERAMIC CHIP	1uF	20%	16V
C722	1-114-219-21	CERAMIC CHIP	1uF	10%	10V
* C723	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
* C724	1-116-738-11	CERAMIC CHIP	1uF	10%	6.3V
C725	1-116-734-11	CERAMIC CHIP	1uF	20%	16V
C726	1-116-734-11	CERAMIC CHIP	1uF	20%	16V
* C732	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
* C733	1-112-716-11	CERAMIC CHIP	0.1uF	10%	6.3V
C735	1-118-403-11	CERAMIC CHIP	0.001uF	10%	50V
		< CONNECTOR >			
* CN401	1-821-503-11	CONNECTOR, FPC (ZIF) 39P			
CN701	1-818-682-71	CONNECTOR, FPC (ZIF) 33P			
* CN702	1-821-501-11	CONNECTOR, FPC (ZIF) 51P			
* CN703	1-821-501-11	CONNECTOR, FPC (ZIF) 51P			
CN705	(Not supplied)	SOCKET, USB CONNECTOR			
CN706	(Not supplied)	CONNECTOR, HDMI (TYPE-D)			
CN707	1-822-837-31	CARD CONNECTOR			
CN709	1-816-655-61	CONNECTOR, FFC/FPC 8P			
		< COMPOSITION CIRCUIT BLOCK >			
CP501	(Not supplied)	WLAN MODULE			
		< DIODE >			
* D001	6-502-629-01	DIODE 1SS420 (TL3SONY.F)			
D002	(Not supplied)	DIODE RBE05SM20AGJT2R			
* D201	6-502-988-01	DIODE RB480Y-40T2R			
D202	6-503-126-01	DIODE DA2S10100K8			

Ref. No.	Part No.	Description			
D701	6-503-126-01	DIODE DA2S10100K8			
D702	6-502-193-01	DIODE SML-D12V8WT86SN			
D703	6-502-934-01	DIODE DB2S31100K8			
D704	6-502-934-01	DIODE DB2S31100K8			
		< FUSE >			
⚠F051	1-576-415-31	FUSE (2A/32V)			
⚠F052	1-576-415-31	FUSE (2A/32V)			
⚠* F053	1-576-843-31	FUSE (0.8A/32V)			
		< FERRITE BEAD >			
FB201	1-469-580-21	INDUCTOR, FERRITE BEAD (1005)			
FB202	1-469-580-21	INDUCTOR, FERRITE BEAD (1005)			
FB351	1-481-912-21	EMI FERRITE (SMD) (1005)			
		< IC >			
IC001	(Not supplied)	IC MB44C031PW-G-ER2E1			
IC002	6-716-873-01	IC RP109L111DA-TR			
IC003	(Not supplied)	IC MM3376A50RRE			
IC051	(Not supplied)	IC MAX14648EWA+TG1A			
IC101	6-716-838-01	IC BU76381GUW-E2			
IC211	(Not supplied)	IC OLY2G2G27A			
IC401	6-716-760-01	IC R2J30503LG			
IC402	6-715-211-01	IC MM3404A28URE			
IC503	(Not supplied)	IC BDS2DJ22GUL-E2			
		< COIL >			
L001	1-481-926-11	INDUCTOR	2.2uH		
L002	(Not supplied)	INDUCTOR	4.7uH		
L003	(Not supplied)	INDUCTOR	4.7uH		
L004	1-481-926-11	INDUCTOR	2.2uH		
L005	(Not supplied)	INDUCTOR	1.5uH		
L006	(Not supplied)	INDUCTOR	22uH		
		< LINE FILTER >			
* LF704	1-457-443-22	COMMON MODE CHOKE COIL			
		< TRANSISTOR >			
Q051	6-552-999-01	TRANSISTOR	RW1E025RPT2CR		
Q201	6-552-765-01	TRANSISTOR	FC6943010R		
* Q202	6-553-023-01	TRANSISTOR	FK3303010L		
* Q261	6-553-023-01	TRANSISTOR	FK3303010L		
		< RESISTOR >			
R002	1-211-969-11	METAL CHIP	10	0.5%	1/10W
R052	1-208-935-11	METAL CHIP	100K	0.5%	1/16W
R105	1-218-957-11	METAL CHIP	2.2K	5%	1/16W
R106	1-218-957-11	METAL CHIP	2.2K	5%	1/16W
* R204	1-250-477-11	METAL CHIP	180	1%	1/16W
R207	1-250-515-11	METAL CHIP	6.8K	1%	1/16W
R210	1-218-961-11	METAL CHIP	4.7K	5%	1/16W
R211	1-218-953-11	METAL CHIP	1K	5%	1/16W
R212	1-218-965-11	METAL CHIP	10K	5%	1/16W
R214	1-218-961-11	METAL CHIP	4.7K	5%	1/16W
R216	1-218-970-11	METAL CHIP	27K	5%	1/16W
R220	1-218-941-81	METAL CHIP	100	5%	1/16W
R222	1-218-956-11	METAL CHIP	1.8K	5%	1/16W
R223	1-218-956-11	METAL CHIP	1.8K	5%	1/16W

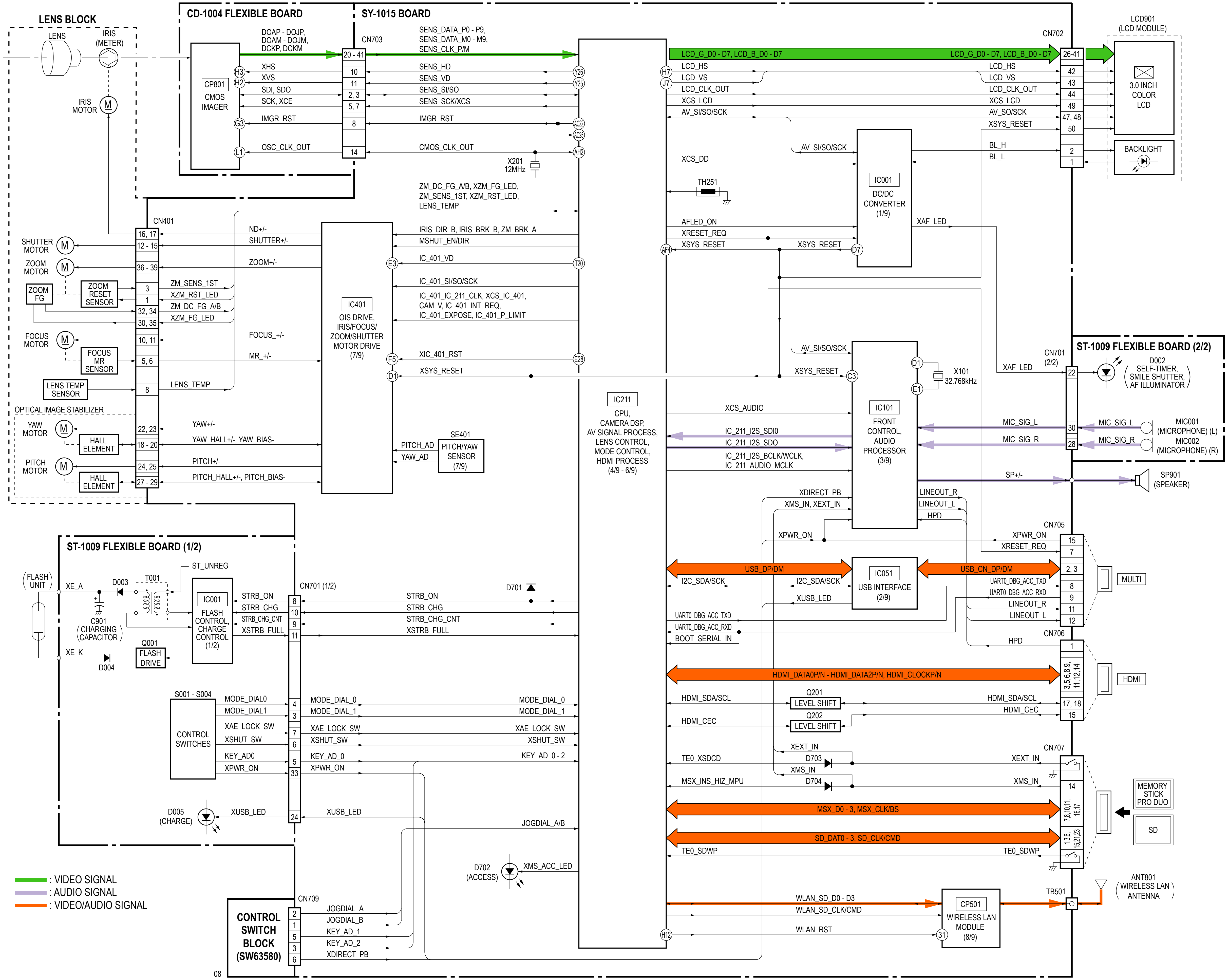
Ref. No.	Part No.	Description			
R252	1-218-941-81	METAL CHIP	100	5%	1/16W
R258	1-218-941-81	METAL CHIP	100	5%	1/16W
R259	1-218-941-81	METAL CHIP	100	5%	1/16W
R264	1-218-961-11	METAL CHIP	4.7K	5%	1/16W
R265	1-218-941-81	METAL CHIP	100	5%	1/16W
R266	1-218-961-11	METAL CHIP	4.7K	5%	1/16W
R286	1-218-947-11	METAL CHIP	330	5%	1/16W
R292	(Not supplied)	METAL CHIP	100K	1%	1/20W
R293	1-218-965-11	METAL CHIP	10K	5%	1/16W
R299	1-208-943-11	METAL CHIP	220K	0.5%	1/16W
R300	1-218-973-11	METAL CHIP	47K	5%	1/16W
R301	1-208-943-11	METAL CHIP	220K	0.5%	1/16W
R351	1-208-668-11	METAL CHIP	240	0.5%	1/16W
R435	1-208-911-11	METAL CHIP	10K	0.5%	1/16W
R436	1-218-848-11	METAL CHIP	1.1K	0.5%	1/10W
* R438	1-248-350-11	RES-CHIP	1.5	1%	1/3W
R440	1-208-711-11	METAL CHIP	15K	0.5%	1/16W
R453	1-218-965-11	METAL CHIP	10K	5%	1/16W
R454	1-218-965-11	METAL CHIP	10K	5%	1/16W
* R468	1-250-493-11	METAL CHIP	820	1%	1/16W
* R469	1-250-493-11	METAL CHIP	820	1%	1/16W
R470	1-250-483-11	METAL CHIP	330	1%	1/16W
R471	1-218-973-11	METAL CHIP	47K	5%	1/16W
R472	1-208-721-11	METAL CHIP	39K	0.5%	1/16W
R473	1-208-721-11	METAL CHIP	39K	0.5%	1/16W
R474	1-218-958-11	METAL CHIP	2.7K	5%	1/16W
R475	1-218-958-11	METAL CHIP	2.7K	5%	1/16W
R476	1-208-703-11	METAL CHIP	6.8K	0.5%	1/16W
R477	1-208-703-11	METAL CHIP	6.8K	0.5%	1/16W
R505	1-240-683-91	METAL CHIP	100	5%	1/20W
R506	1-240-683-91	METAL CHIP	100	5%	1/20W
R509	1-218-990-81	SHORT CHIP	0		
R701	1-218-945-11	METAL CHIP	220	5%	1/16W
R704	1-218-945-11	METAL CHIP	220	5%	1/16W
R717	1-218-953-11	METAL CHIP	1K	5%	1/16W
R733	1-218-955-11	METAL CHIP	1.5K	5%	1/16W
		< COMPOSITION CIRCUIT BLOCK >			
RB201	1-234-372-11	RES, NETWORK	100 (1005X4)		
RB202	1-234-373-21	RES, NETWORK	220 (1005X4)		
RB203	1-234-378-21	RES, NETWORK	10K (1005X4)		
* RB204	1-200-108-21	RES, NETWORK	680 (1005X4)		
* RB205	1-200-108-21	RES, NETWORK	680 (1005X4)		
RB501	1-234-372-11	RES, NETWORK	100 (1005X4)		
		< SENSOR >			
SE401	8-826-002-52	GYRO SENSOR GSU-X370D/N-S(1) (PITCH/YAW)			
		< TERMINAL >			
TB501	(Not supplied)	TERMINAL, ANTENNA			
		< THERMISTOR >			
TH251	1-805-194-21	THERMISTOR, NTC (SMD)			

Ref. No.	Part No.	Description
		< VIBRATOR >
X101	1-781-525-11	VIBRATOR, CRYSTAL (32.768kHz)
X201	1-487-897-31	SILICON OSCILLATOR (12MHz)

4. BLOCK DIAGRAMS

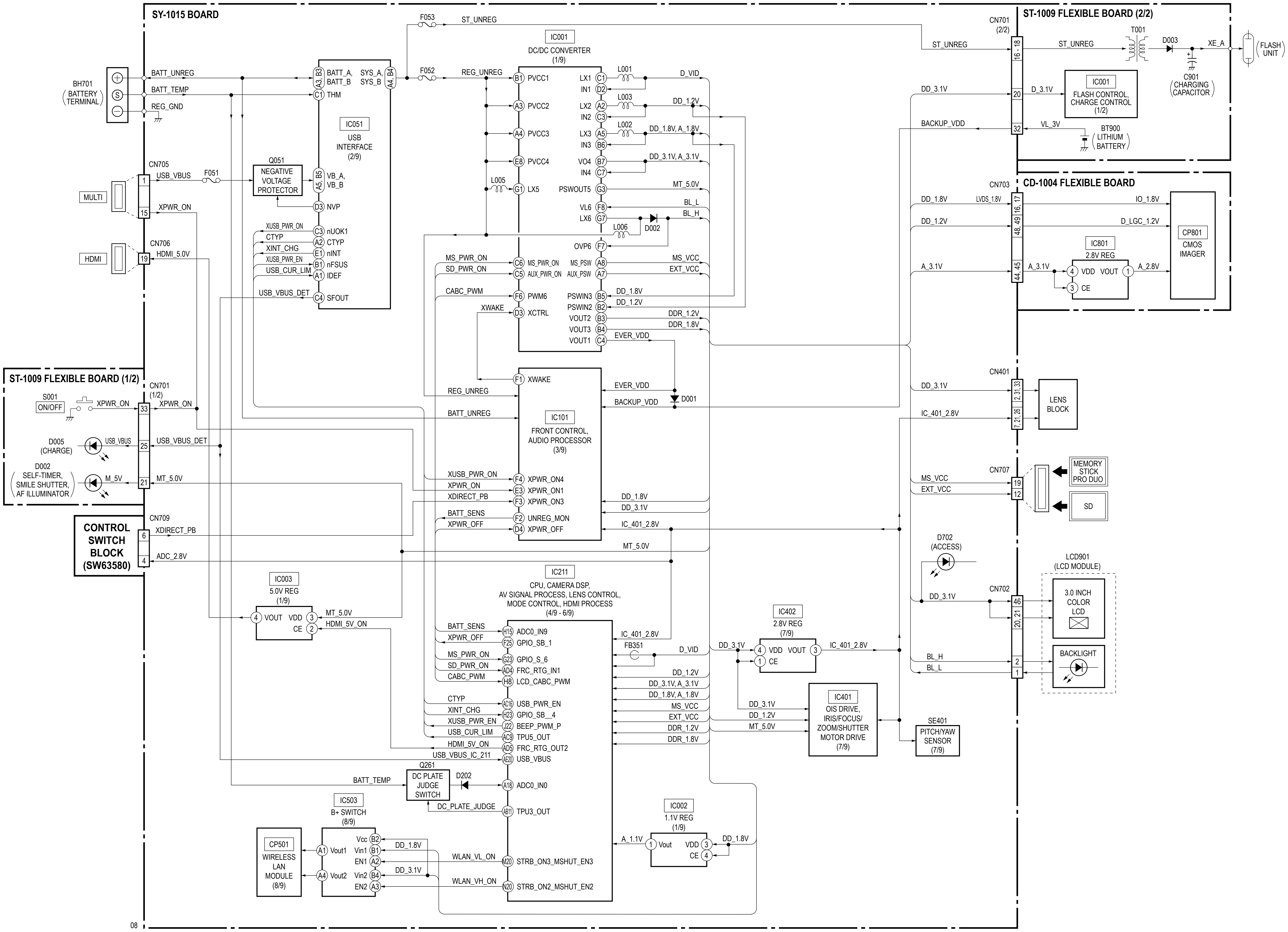
4-1. OVERALL BLOCK DIAGRAM

( ) : Number in parenthesis ( ) indicates the division number of schematic diagram where the component is located.



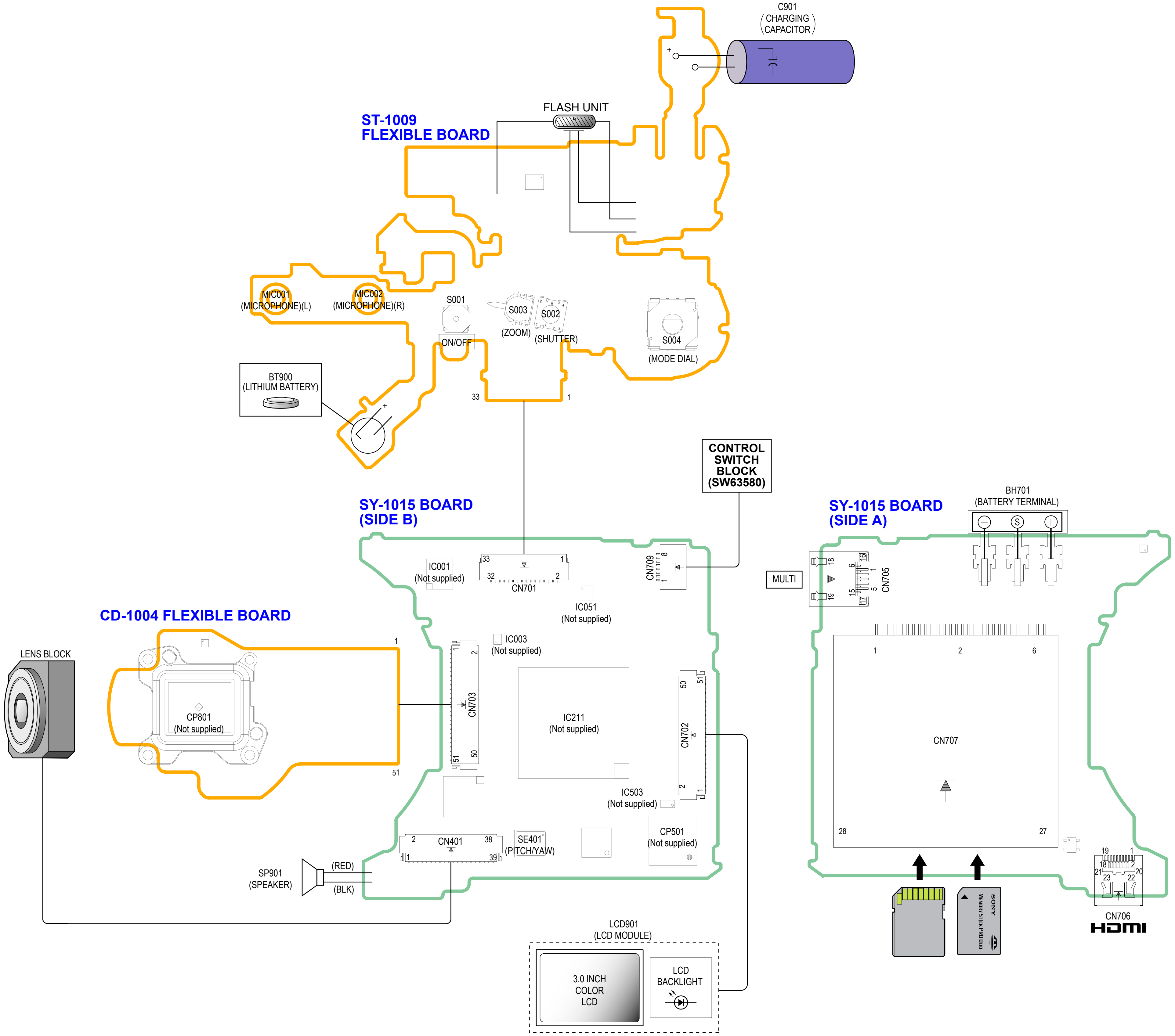
4-2. POWER BLOCK DIAGRAM

( ) : Number in parenthesis ( ) indicates the division number of schematic diagram where the component is located.



DSC-WX300_L3

5. FRAME SCHEMATIC DIAGRAMS



6. SCHEMATIC DIAGRAMS AND PRINTED WIRING BOARDS

– ENGLISH –

THIS NOTE IS COMMON FOR SCHEMATIC DIAGRAMS AND PRINTED WIRING BOARDS.
(In addition to this, the necessary note is printed in each block.)

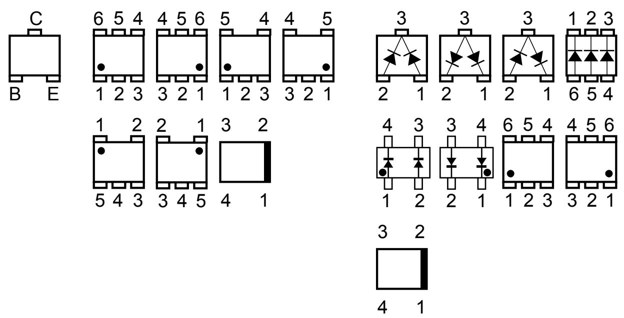
For Schematic Diagrams

- All capacitors are in μF unless otherwise noted. pF : μ μF. 50 V or less are not indicated except for electrolytics and tantalums.
- Chip resistors are 1/10 W unless otherwise noted. kΩ=1000 Ω, MΩ=1000 kΩ.
- Caution when replacing chip parts.
  New parts must be attached after removal of chip.
  Be careful not to heat the minus side of tantalum capacitor, Because it is damaged by the heat.
- Some chip part will be indicated as follows.
  Example C541 L452
  22U 10UH
  TA A 2520
  Kinds of capacitor | External dimensions (mm)
  Case size
- Constants of resistors, capacitors, ICs and etc with XX indicate that they are not used.
  In such cases, the unused circuits may be indicated.
- Parts with ★ differ according to the model/destination.
  Refer to the mount table for each function.
- All variable and adjustable resistors have characteristic curve B, unless otherwise noted.
- Signal name
  XEDIT → $\overline{\text{EDIT}}$ PB/XREC → PB/$\overline{\text{REC}}$
- : non flammable resistor
- : fusible resistor
- : panel designation
- : B+ Line
- : B– Line
- : IN/OUT direction of (+, –) B LINE.
- : adjustment for repair.

For Printed Wiring Boards

- : Uses unleaded solder.
- : Circuit board
  : Flexible board
  Pattern from the side which enables seeing.
  : pattern of the rear side
  (The other layers' patterns are not indicated)
- Through hole is omitted.
- There are a few cases that the part printed on diagram isn't mounted in this model.
- : panel designation

- Chip parts.
  Transistor Diode



Precautions for Replacement of Imager
- If the imager has been replaced, carry out all the adjustments for the camera section.
- As the imager may be damaged by static electricity from its structure, handle it carefully like for the MOS IC.
  In addition, ensure that the receiver is not covered with dusts nor exposed to strong light.

When indicating parts by reference number, please include the board name.

The components identified by mark ⚠ or dotted line with mark ⚠ are critical for safety.
Replace only with part number specified.

Les composants identifiés par une marque ⚠ sont critiques pour la sécurité.
Ne les remplacer que par une pièce portant le numéro spécifié.

– JAPANESE –

回路図，プリント図共通ノート
（他に必要なノートは各セクションに記載しています）

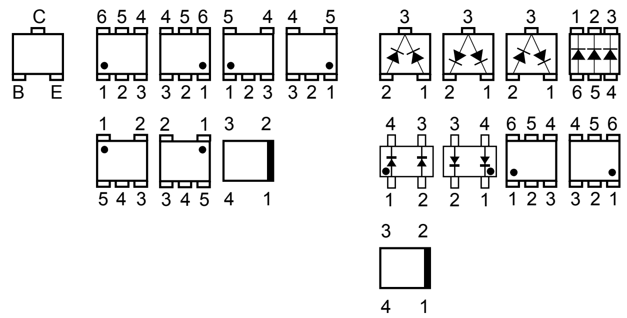
回路図ノート

- ケミコン，タンタルを除くコンデンサで，耐圧50V以下のものはその耐圧を省略。単位はすべてμF(pはpF)。
- チップ抵抗で指示のないものは，1/10W以下。
  kΩ＝1000Ω，MΩ＝1000kΩ
- チップ部品交換時の注意
  取り外した部品は再使用せず，未使用の部品をご使用ください。
  タンタルコンデンサのマイナス側は熱に弱いため注意してください。
- チップ部品には下記のように表示したものがあります。
  例 C541 L452
  22U 10UH
  TA A 2520
  種類 外形寸法(mm)
  ケースサイズ
- 抵抗，コンデンサ，ICなど定数にXXがあるものは，使用していない事を示しています。このため，使用していない回路が記載されている事があります。
- ★印のある部品は，機種などにより異なりますので機能別マウント一覧表を参照してください。
- 可変抵抗と半固定抵抗で，B特性の表示を省略。
- 信号名表記について，下記のような場合があります。
  XEDIT → $\overline{\text{EDIT}}$ PB/XREC → PB/$\overline{\text{REC}}$
- は不燃性抵抗。
- はヒューズ抵抗。
- はパネル表示名称。
- はB＋ライン。
- はB－ライン。
- はBライン(＋，－)の入出力方向を示す。
- は調整名称。

プリント図ノート

- ：無鉛半田を使用しています。
- ：基板
  ：フレキシブル配線板
  見ている面側のパターン。
  ：裏側のパターン
  (他のパターンについては表示されていません)
- スルーホールは省略。
- プリント図には，本機で使用していない部品が記載されている場合があります。
- はパネル表示名称。

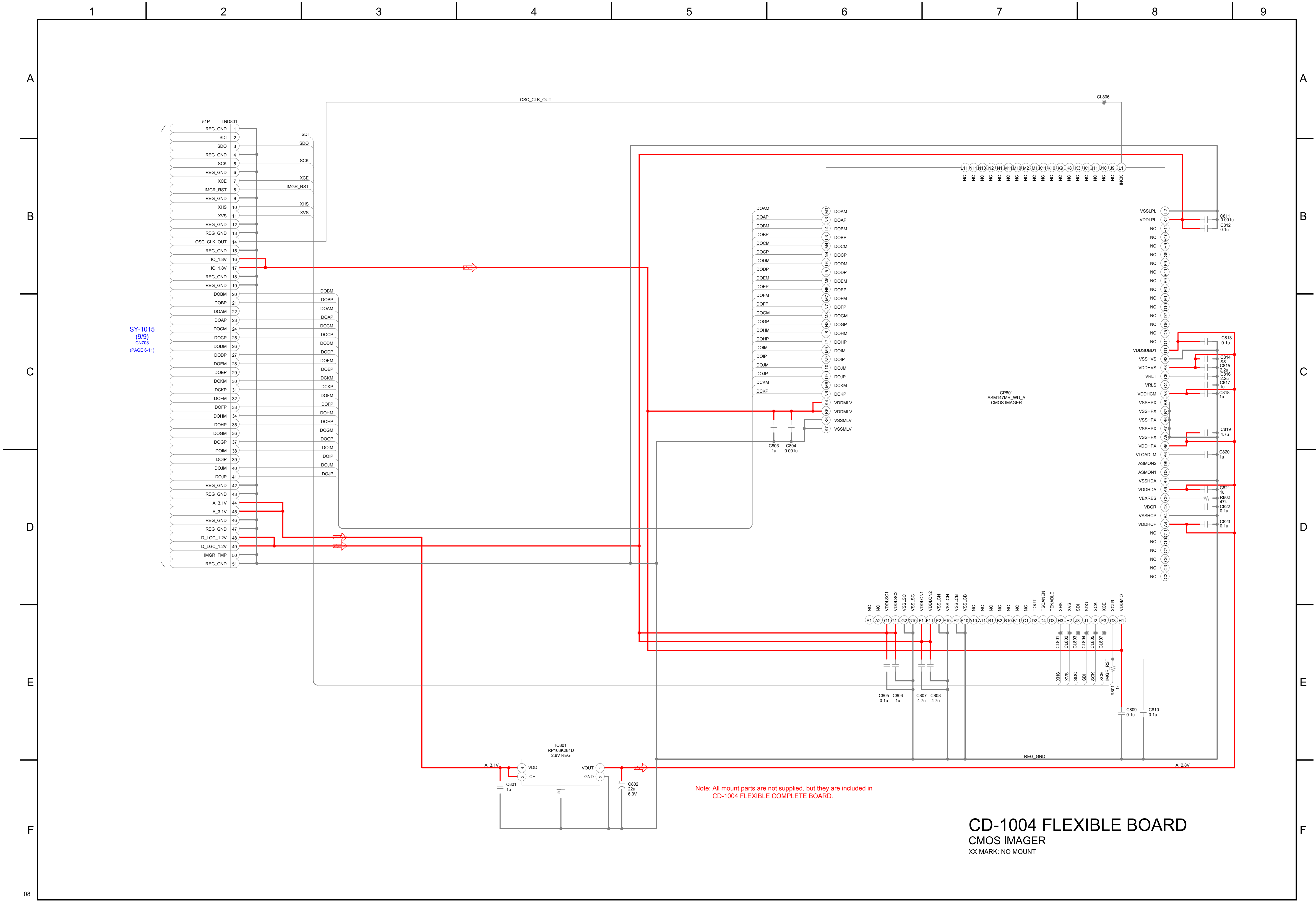
- Chip parts.
  Transistor Diode

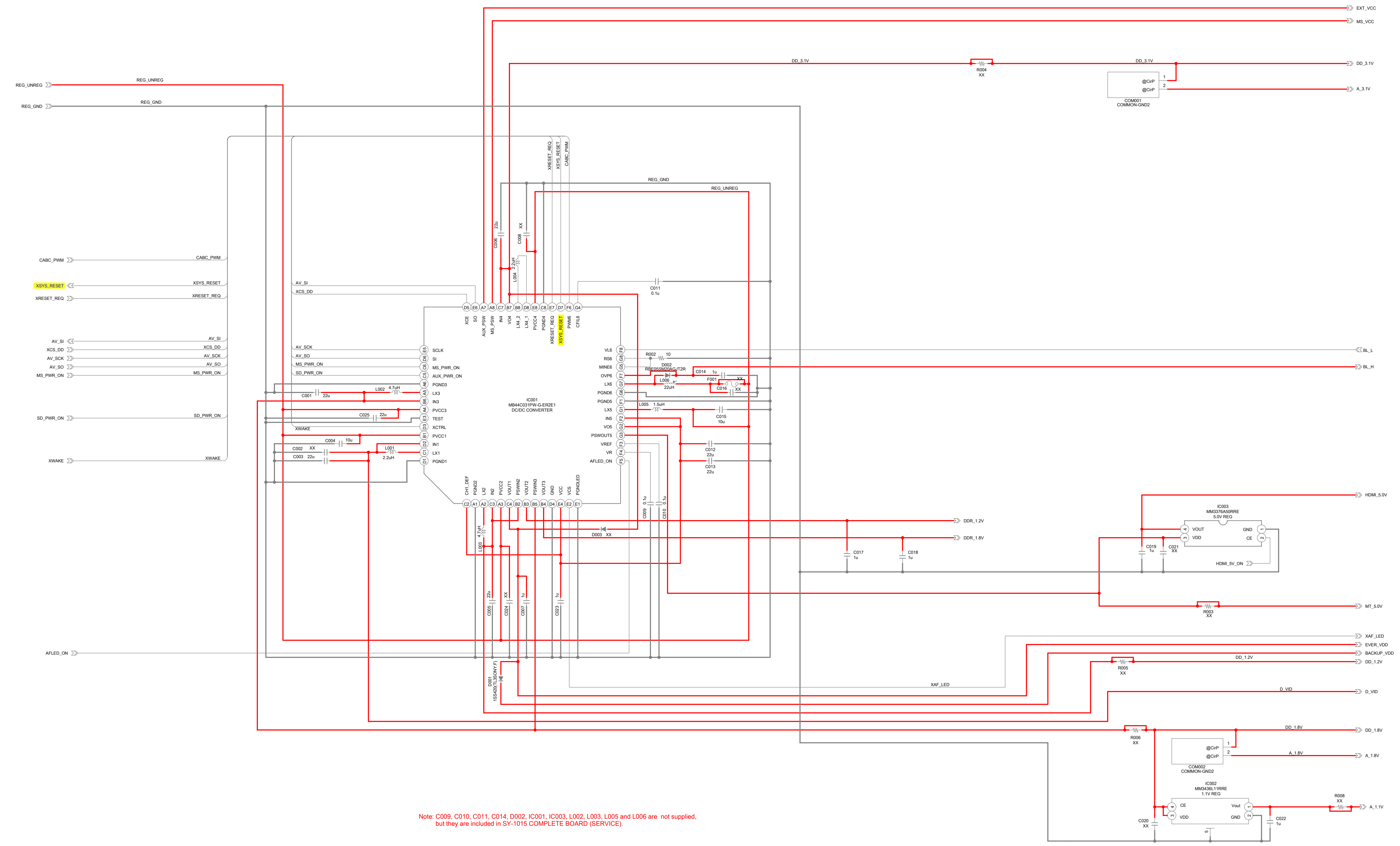


イメージャ交換時の注意
- イメージャを交換した場合は，カメラ部の全調整を行ってください。
- イメージャは構造上，静電気により破壊される恐れがあるため，MOS ICと同様に注意して取り扱ってください。
  また，受光部にはゴミの付着，および強い光がはいることのないように注意してください。

お願い
図面番号で部品を指定するときは基板名又はブロックを併せて指定してください。

⚠印の部品，または⚠印付の点線で囲まれた部品は，安全性を維持するために，重要な部品です。
従って交換時は，必ず指定の部品を使用してください。


SY-1015
(9/9)
CN703
(PAGE 6-11)
51P LND801
OSC_CLK_OUT
CL806
CP801
ASM147MR_WD_A
CMOS IMAGER
IC801
RP103K281D
2.8V REG
REG_GND
A_2.8V
A_3.1V
Note: All mount parts are not supplied, but they are included in
CD-1004 FLEXIBLE COMPLETE BOARD.
CD-1004 FLEXIBLE BOARD
CMOS IMAGER
XX MARK: NO MOUNT
08



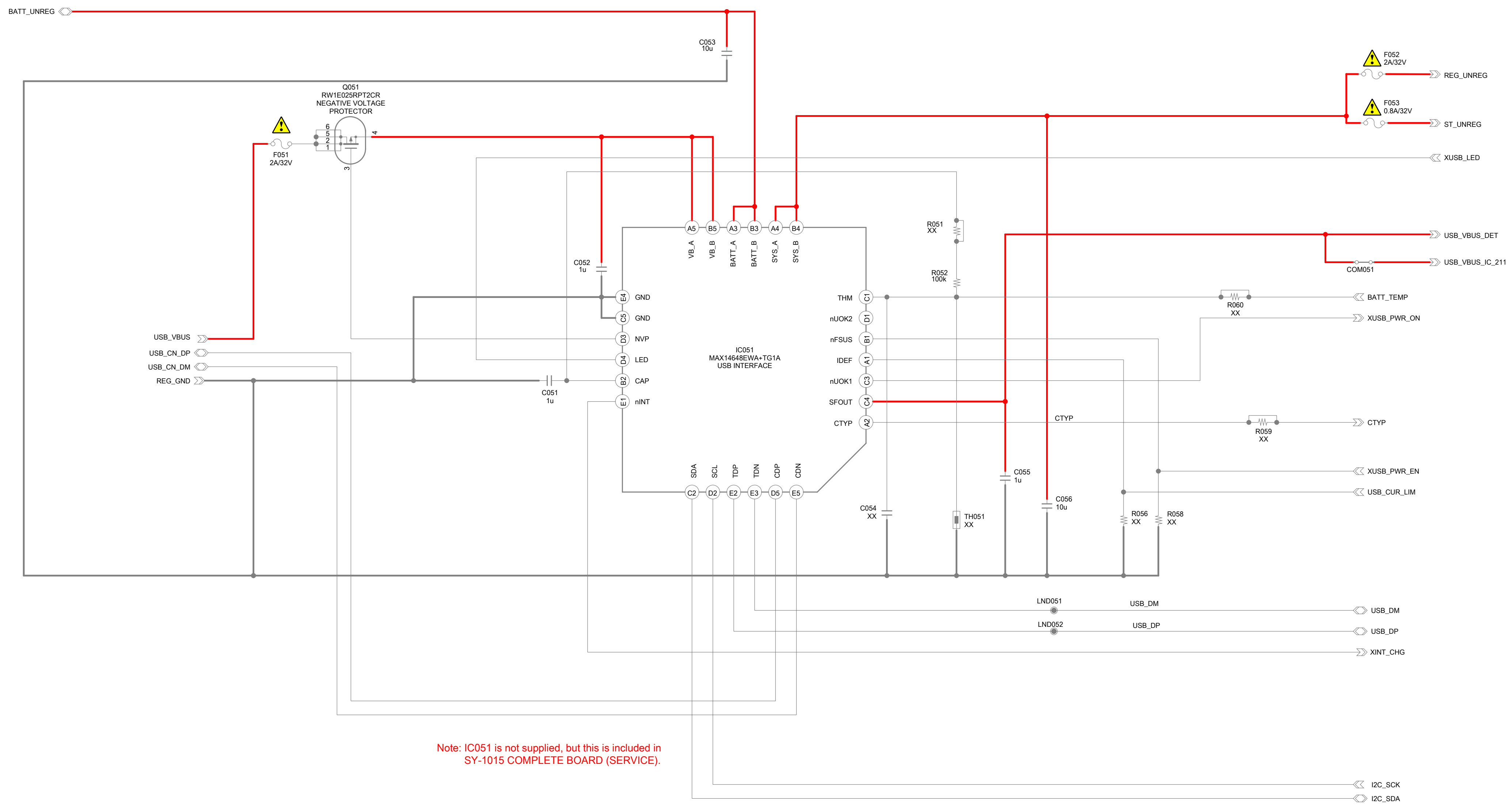
Note: C009, C010, C011, C014, D002, IC001, IC003, L002, L003, L005 and L006 are not supplied, but they are included in SY-1015 COMPLETE BOARD (SERVICE).

SY-1015 BOARD (1/9)

DC/DC CONVERTER

XX MARK: NO MOUNT

08



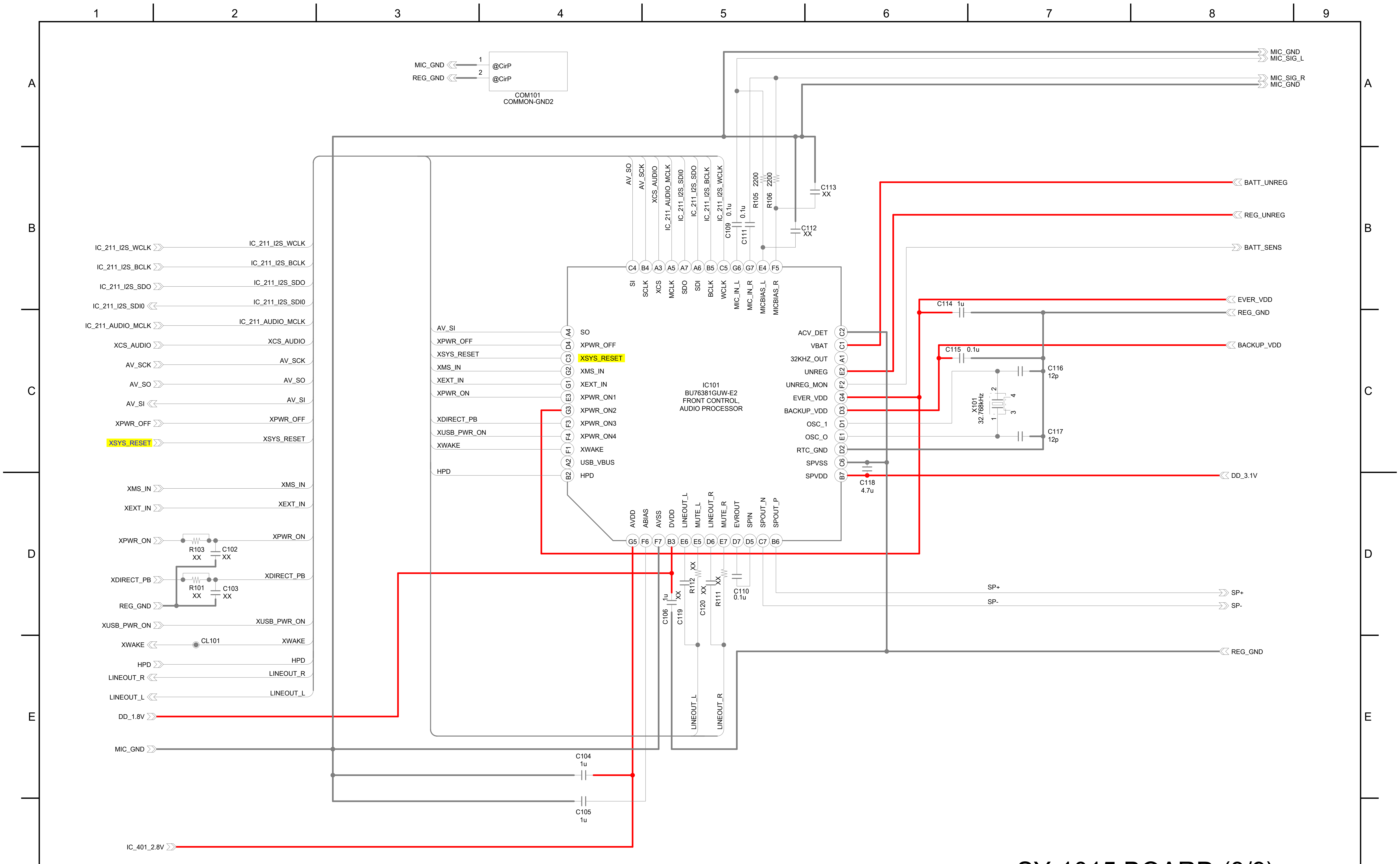
Note: IC051 is not supplied, but this is included in SY-1015 COMPLETE BOARD (SERVICE).

SY-1015 BOARD (2/9)

USB INTERFACE

XX MARK: NO MOUNT

08



Note: C109, C110, C111 and C115 are not supplied,
but they are included in SY-1015 COMPLETE BOARD (SERVICE).

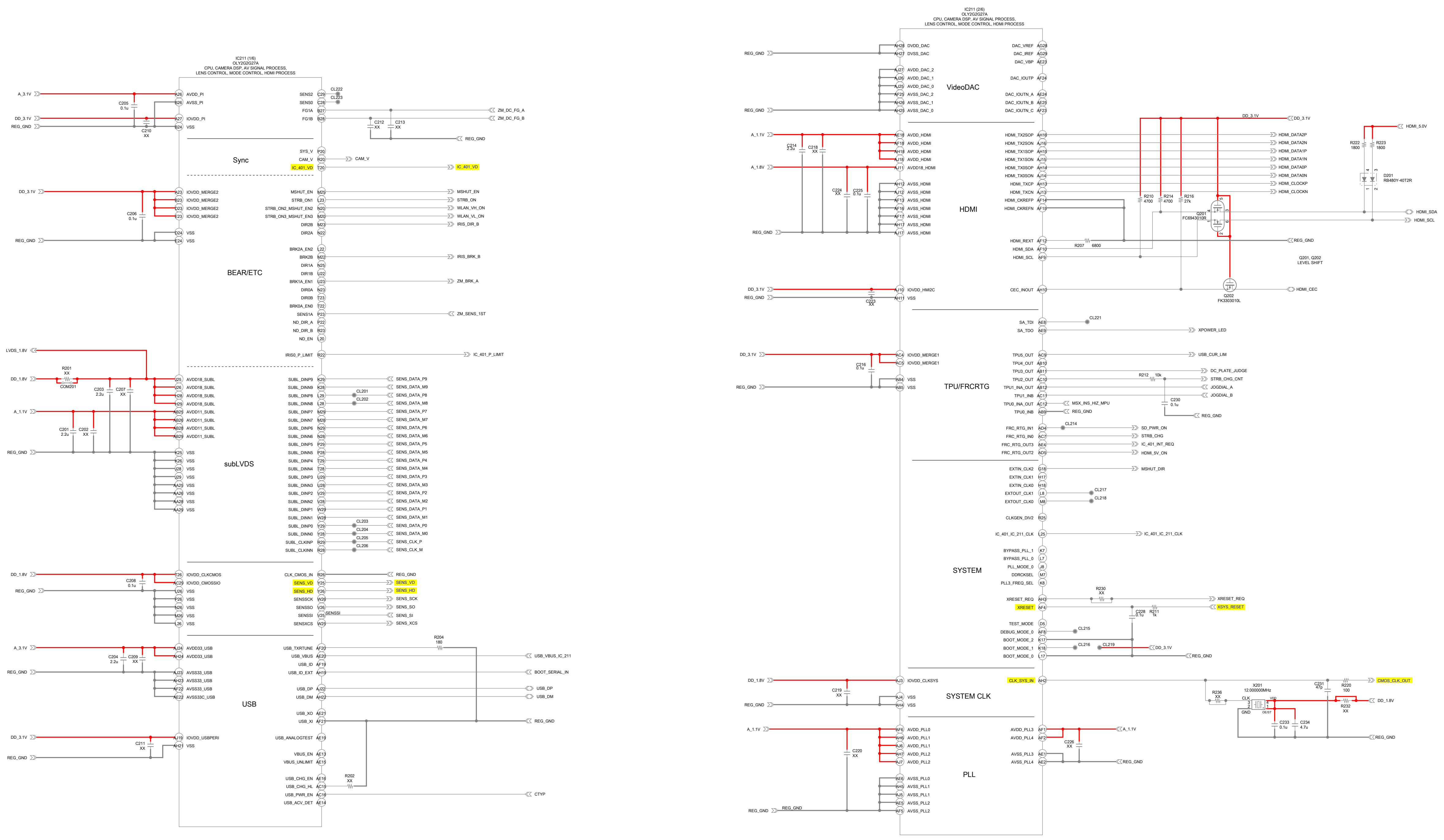
SY-1015 BOARD (3/9)

FRONT CONTROL, AUDIO PROCESSOR

XX MARK: NO MOUNT

08

Note: IC211 is not supplied, but this is included in
SY-1015 COMPLETE BOARD (SERVICE).



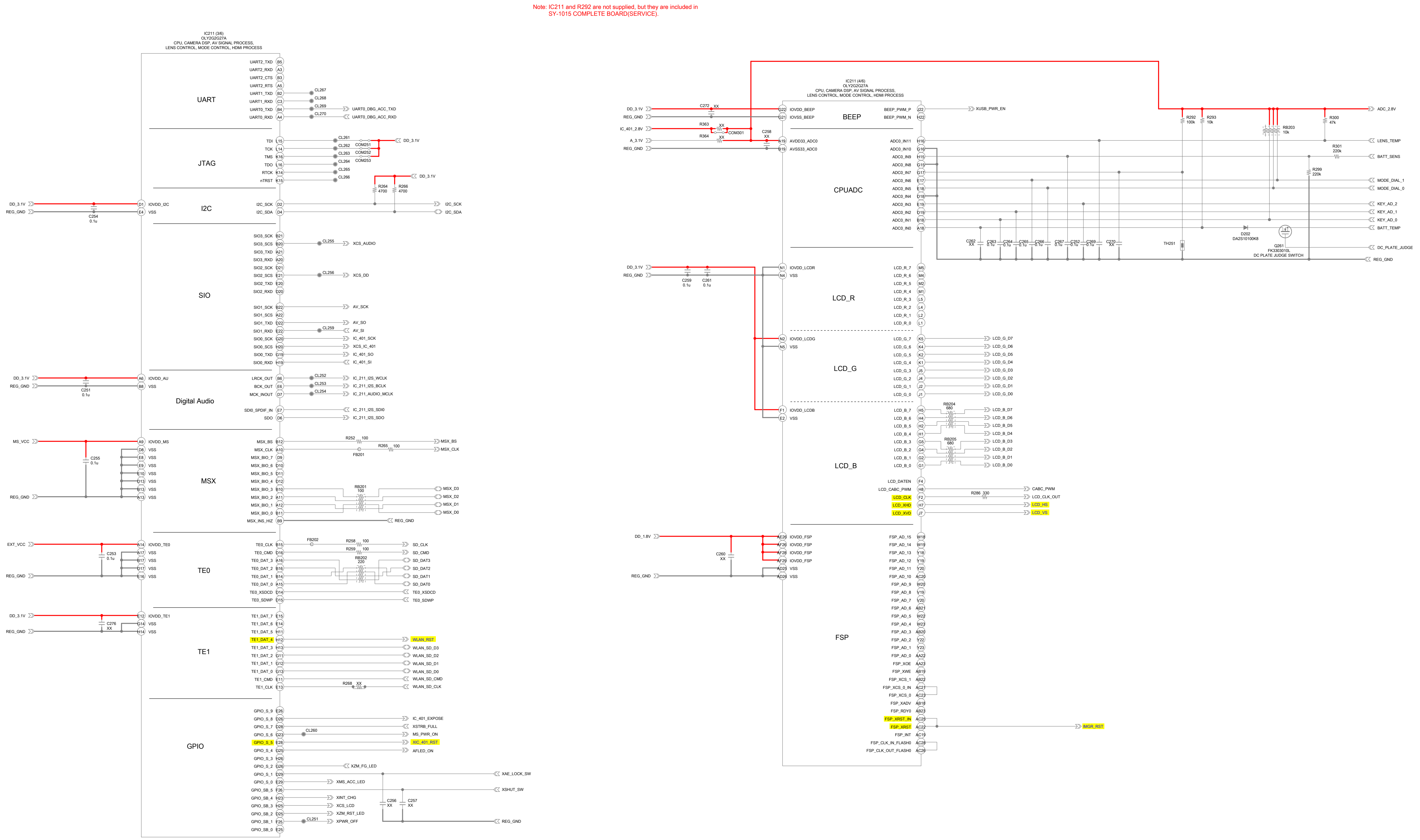
SY-1015 BOARD (4/9)

CPU, CAMERA DSP, AV SIGNAL PROCESS,
LENS CONTROL, MODE CONTROL, HDMI PROCESS (1/3)

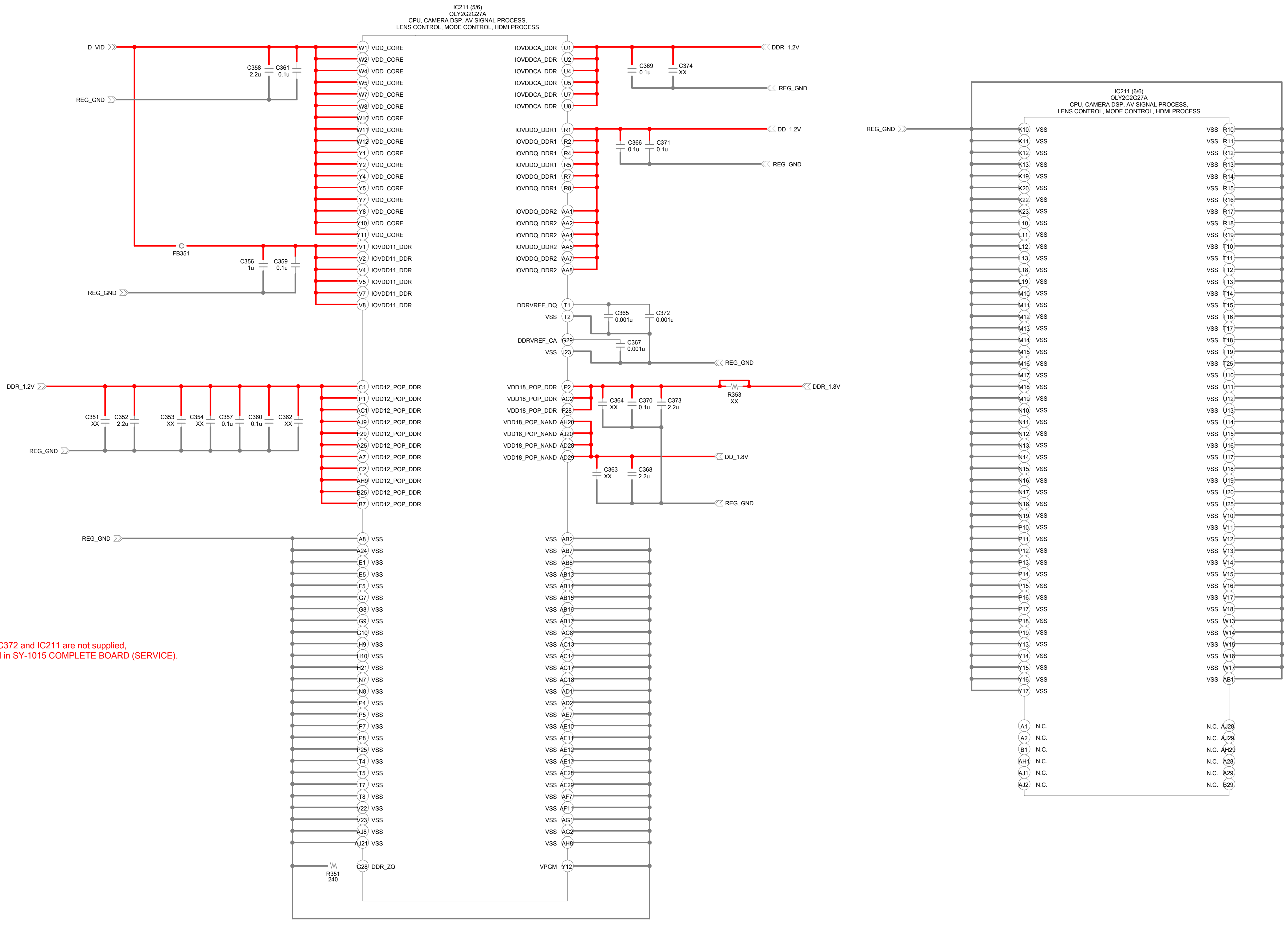
XX MARK: NO MOUNT

08

DSC-WX300_L3



SY-1015 BOARD (5/9)
CPU, CAMERA DSP, AV SIGNAL PROCESS,
LENS CONTROL, MODE CONTROL, HDMI PROCESS (2/3)
XX MARK: NO MOUNT



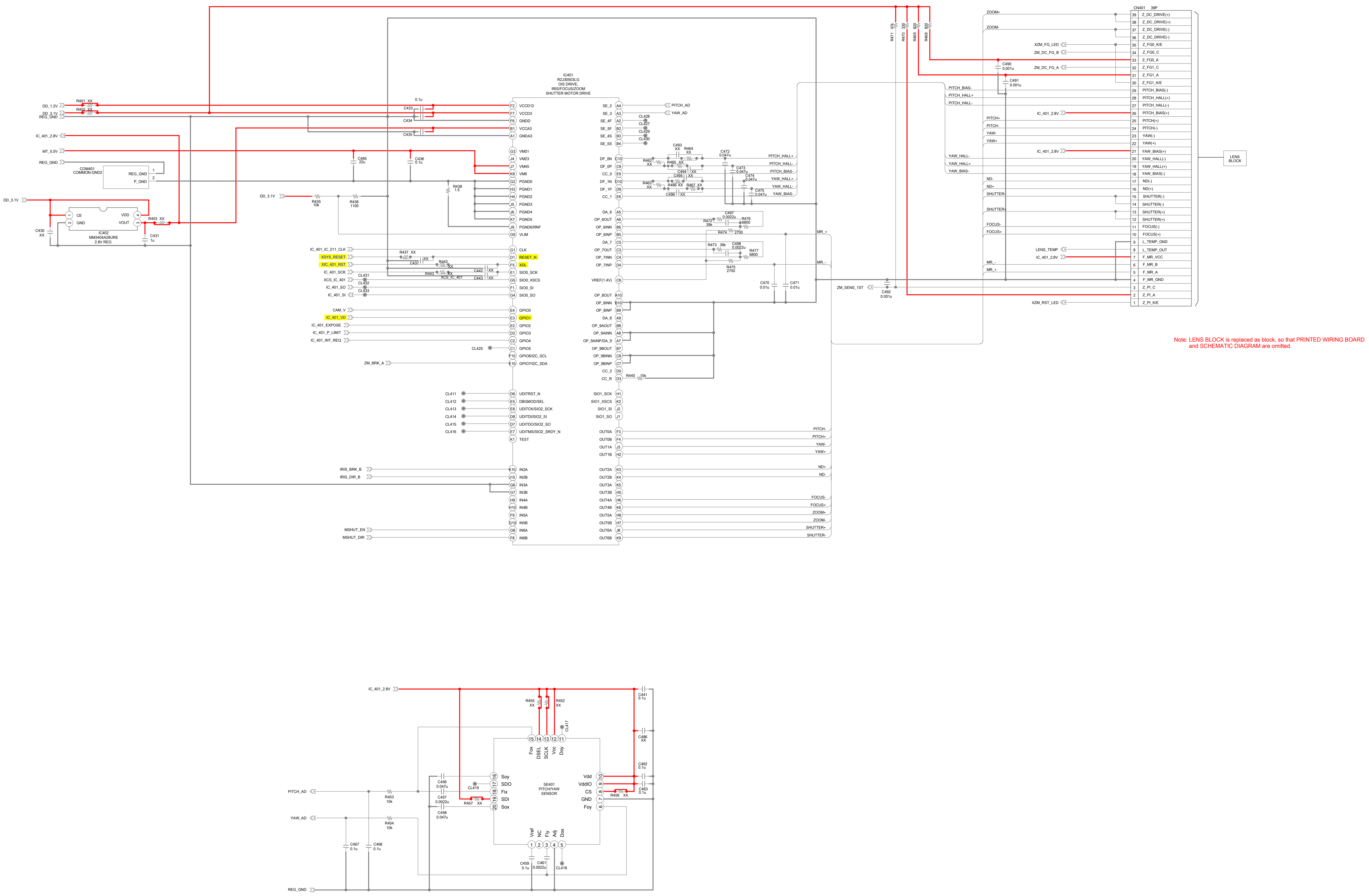
Note: C356, C365, C367, C372 and IC211 are not supplied,
but they are included in SY-1015 COMPLETE BOARD (SERVICE).

SY-1015 BOARD (6/9)

CPU, CAMERA DSP, AV SIGNAL PROCESS,
LENS CONTROL, MODE CONTROL, HDMI PROCESS (3/3)

XX MARK: NO MOUNT

08



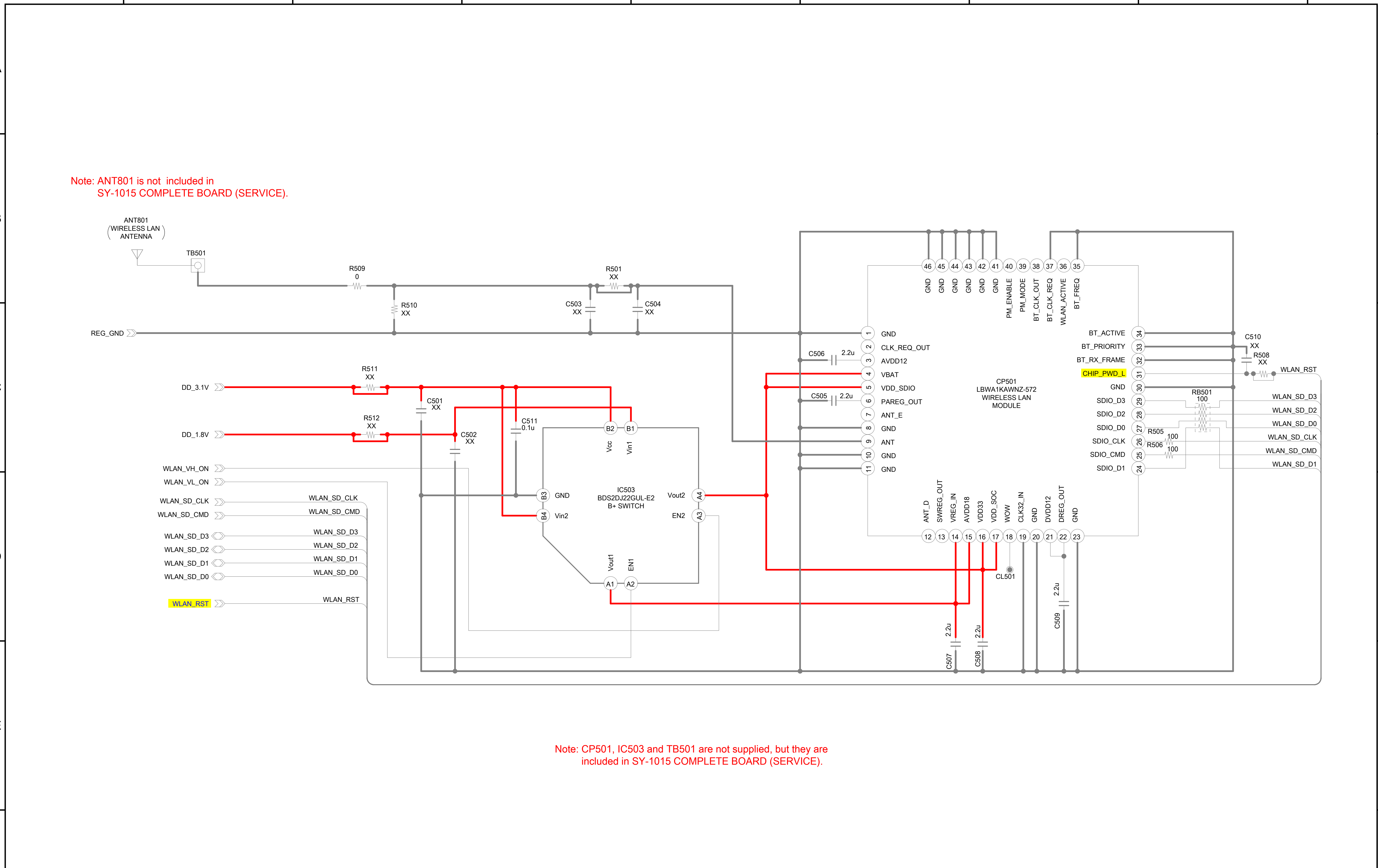
Note: LENS BLOCK is replaced as block, so that PRINTED WIRING BOARD and SCHEMATIC DIAGRAM are omitted.

SY-1015 BOARD (7/9)

OIS DRIVE, FOCUS MOTOR DRIVE,
ZOOM MOTOR DRIVE, SHUTTER MOTOR DRIVE

XX MARK: NO MOUNT

08

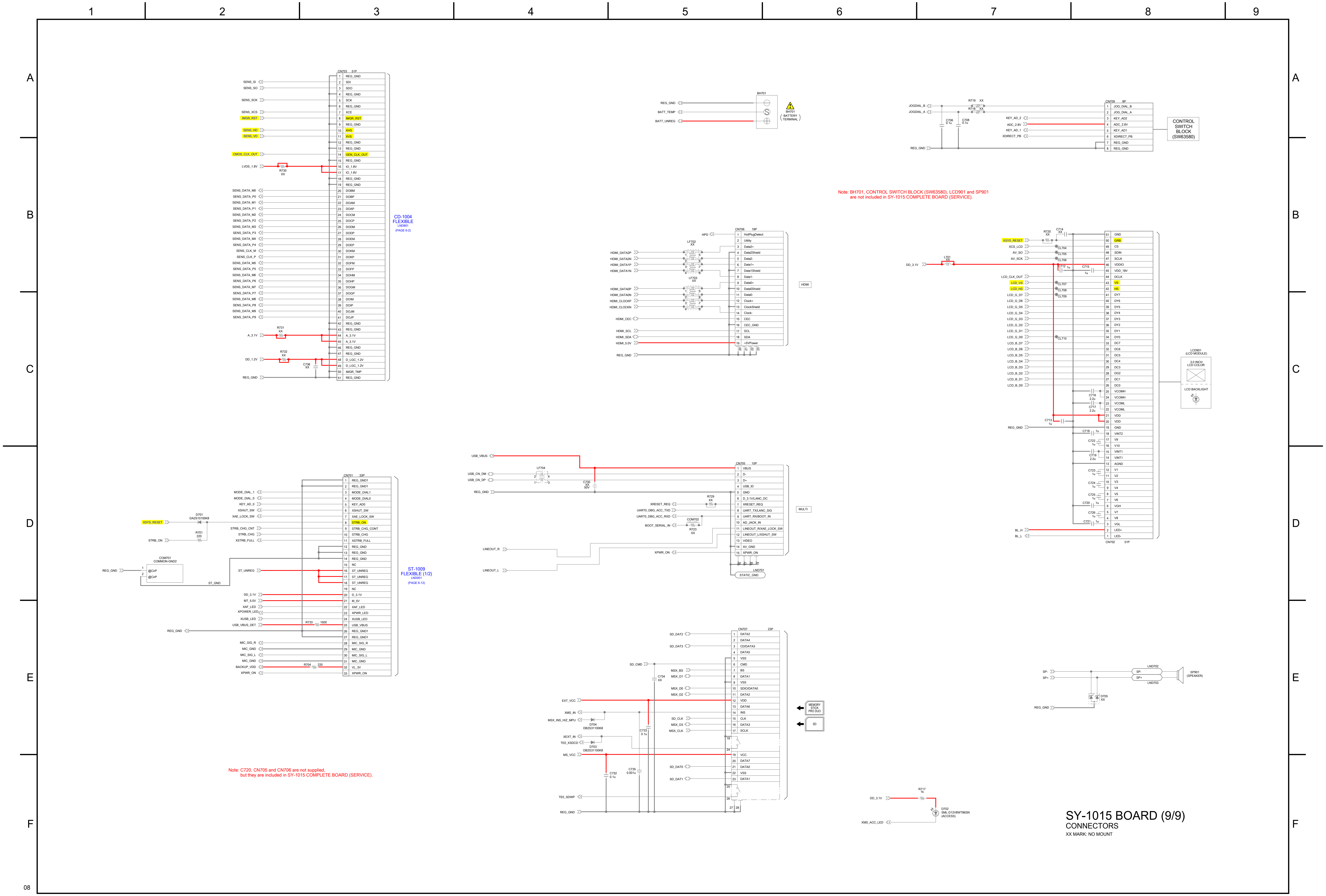


SY-1015 BOARD (8/9)

WIRELESS LAN MODULE

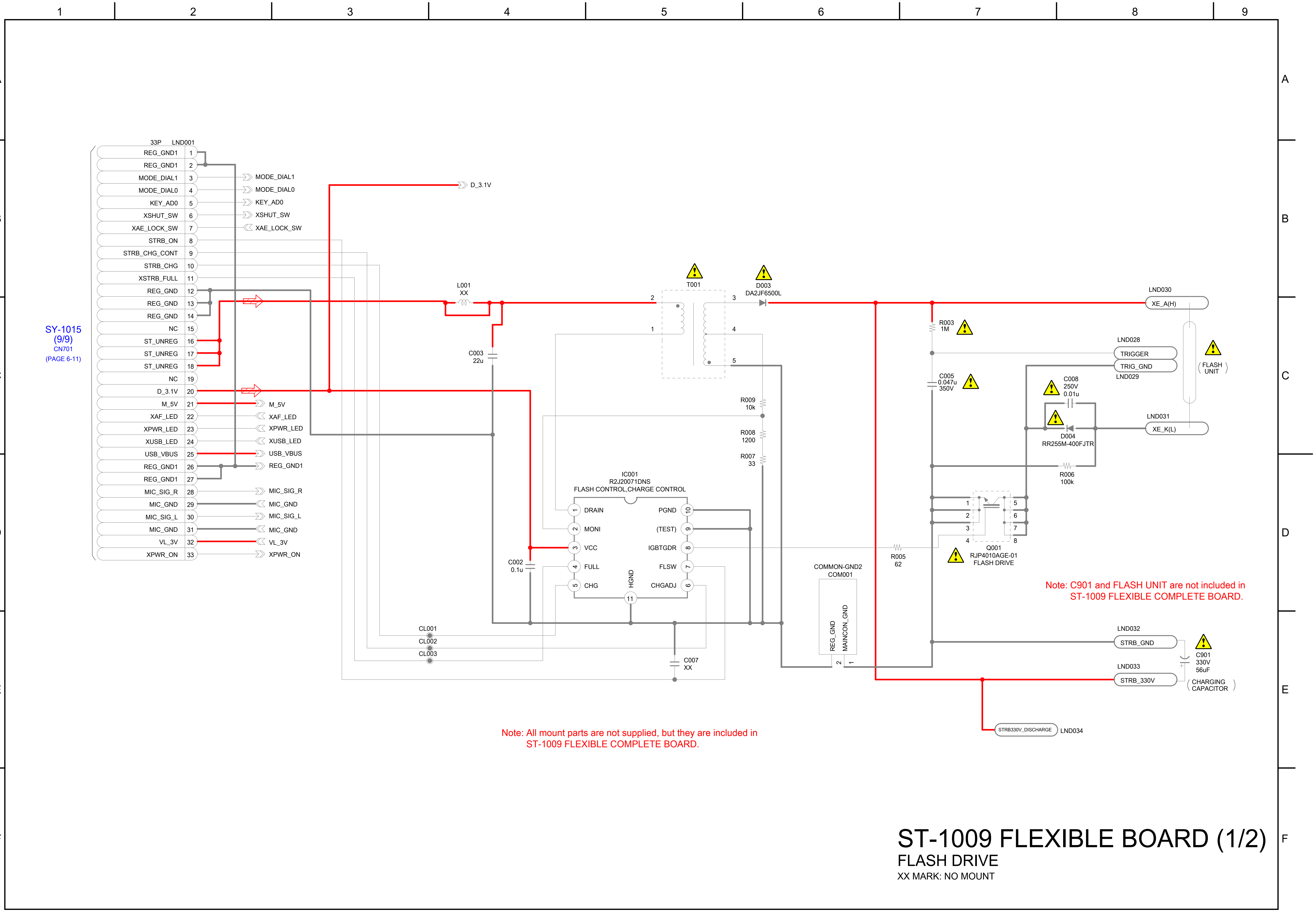
XX MARK: NO MOUNT

08



CD-1004
FLEXIBLE
ST-1009
FLEXIBLE (1/2)
CONTROL
SWITCH
BLOCK
(SW63580)
Note: BH701, CONTROL SWITCH BLOCK (SW63580), LCD901 and SP901 are not included in SY-1015 COMPLETE BOARD (SERVICE).
Note: C720, CN705 and CN706 are not supplied, but they are included in SY-1015 COMPLETE BOARD (SERVICE).
SY-1015 BOARD (9/9)
CONNECTORS
XX MARK: NO MOUNT

08



Note: C901 and FLASH UNIT are not included in ST-1009 FLEXIBLE COMPLETE BOARD.

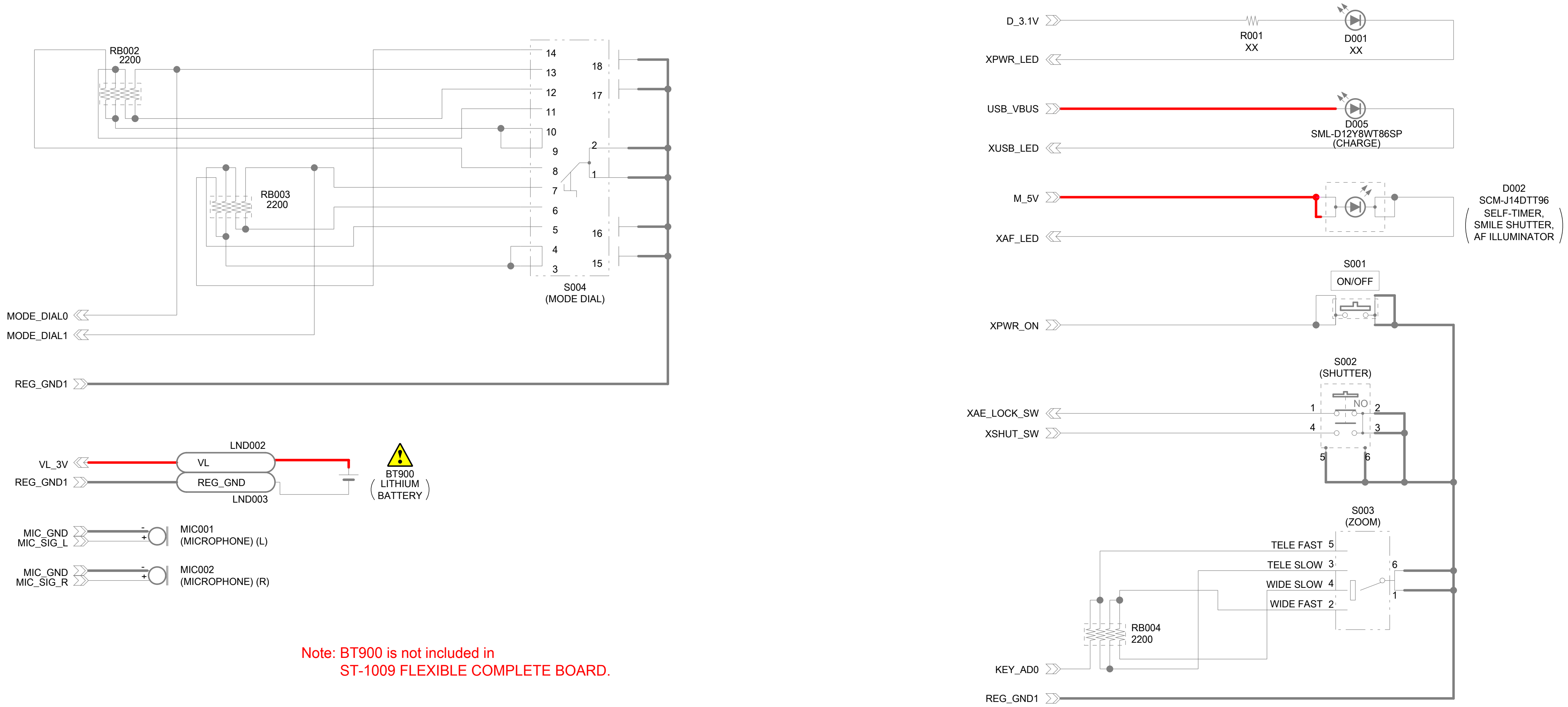
Note: All mount parts are not supplied, but they are included in ST-1009 FLEXIBLE COMPLETE BOARD.

ST-1009 FLEXIBLE BOARD (1/2)

FLASH DRIVE

XX MARK: NO MOUNT

08



Note: BT900 is not included in
ST-1009 FLEXIBLE COMPLETE BOARD.

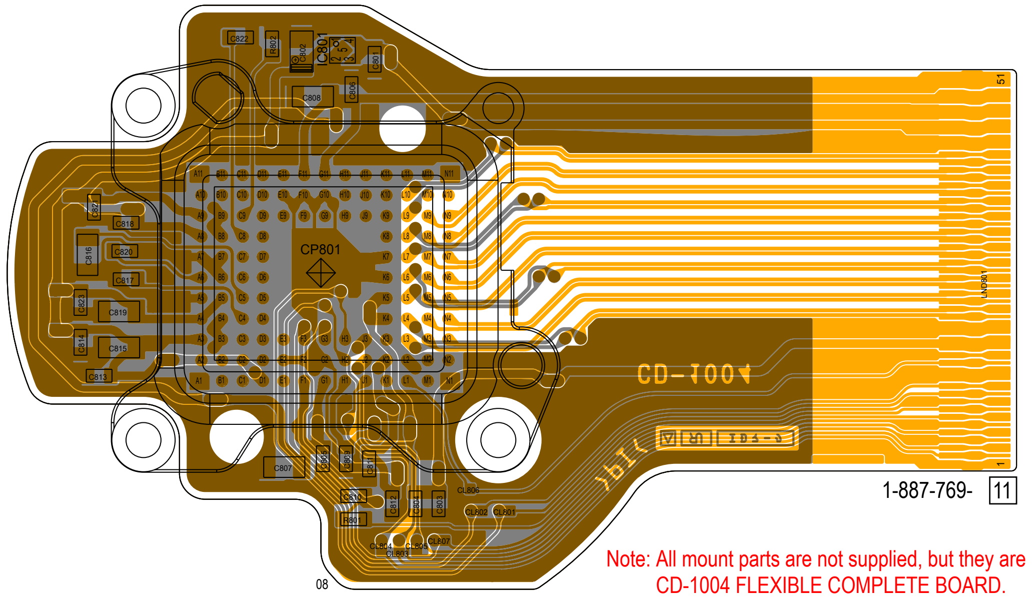
ST-1009 FLEXIBLE BOARD (2/2)

KEY CONTROL

XX MARK: NO MOUNT

08

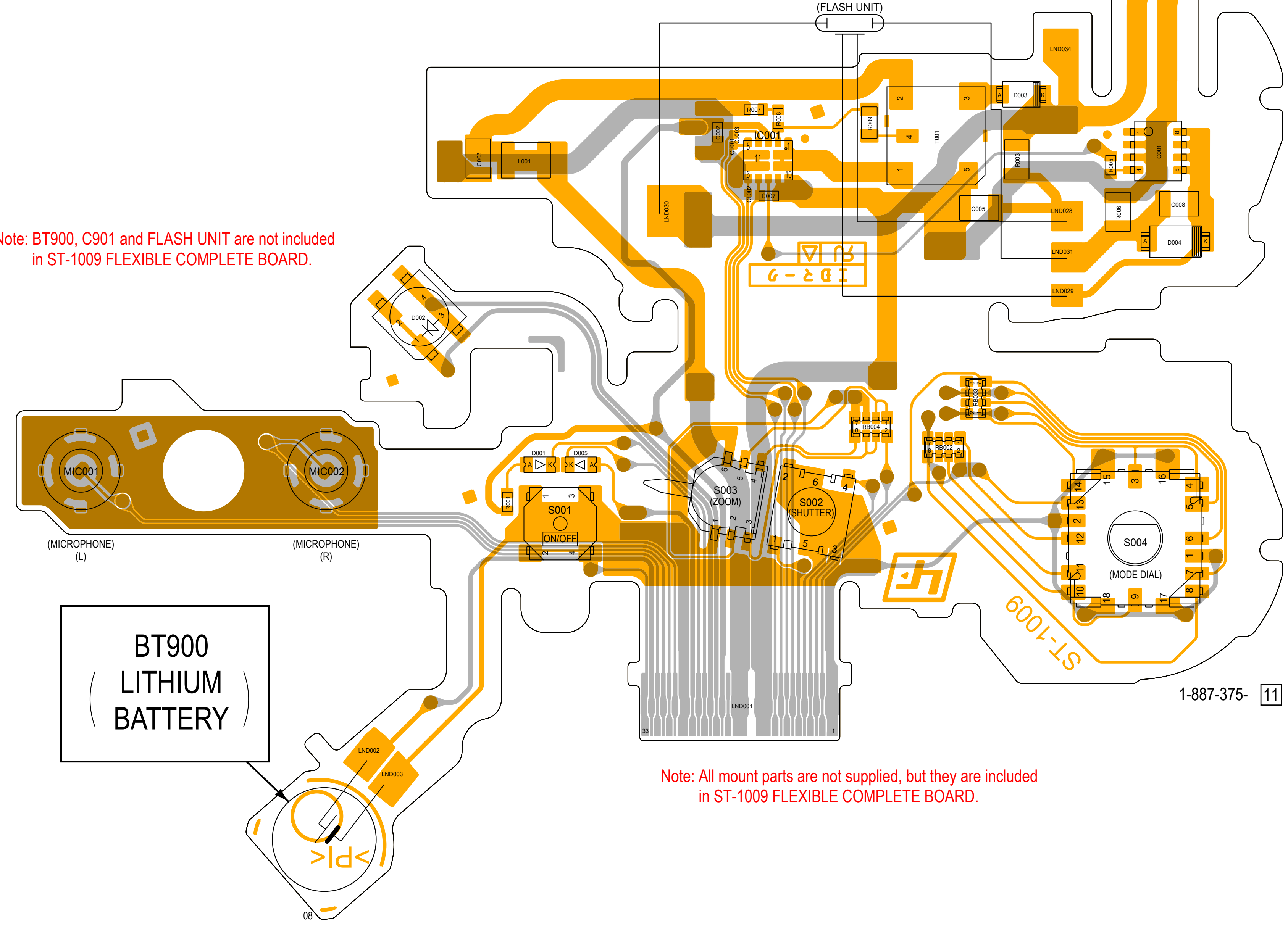
CD-1004 FLEXIBLE BOARD



Note: All mount parts are not supplied, but they are included in CD-1004 FLEXIBLE COMPLETE BOARD.

ST-1009 FLEXIBLE BOARD

Note: BT900, C901 and FLASH UNIT are not included in ST-1009 FLEXIBLE COMPLETE BOARD.



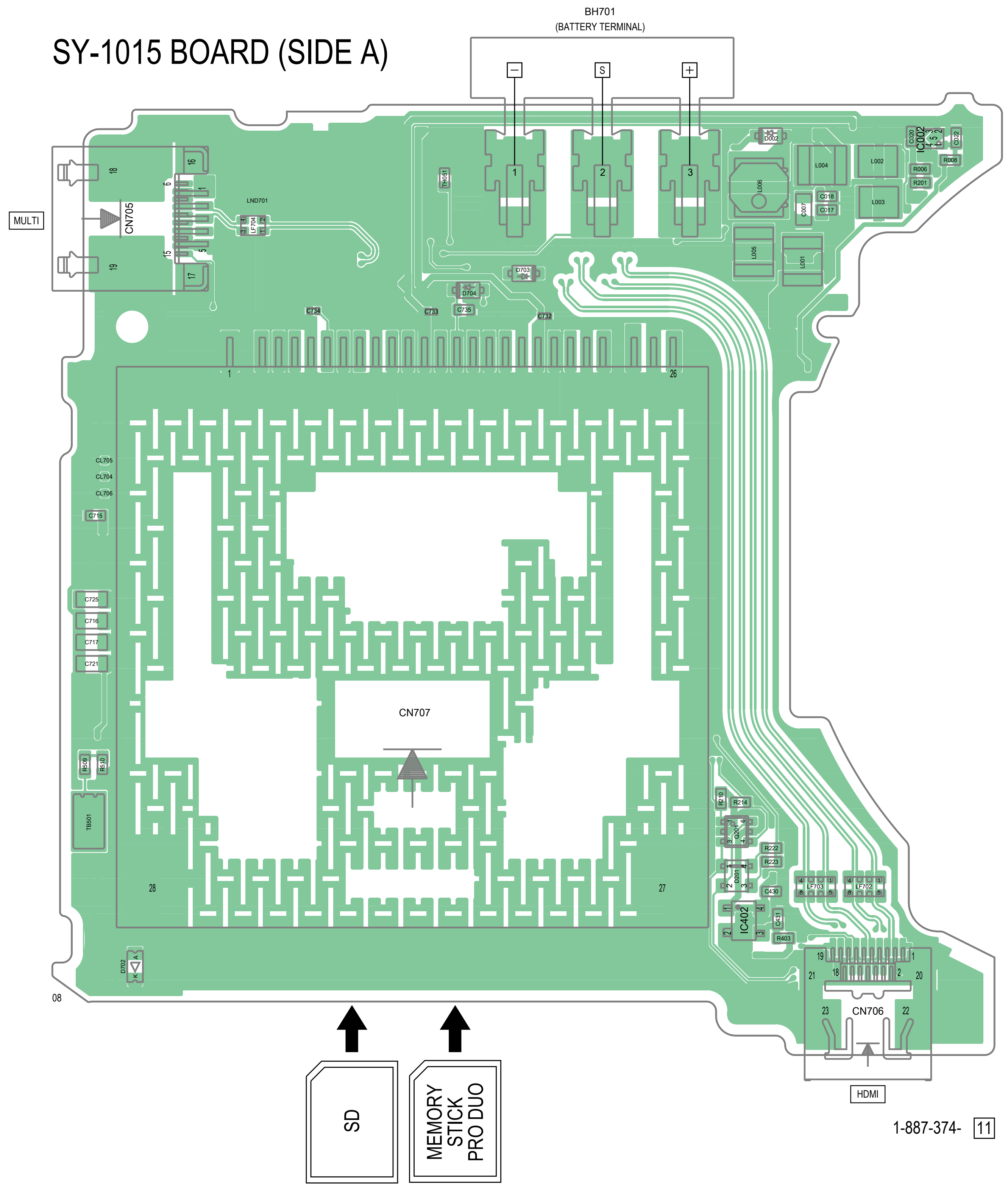
Note: All mount parts are not supplied, but they are included in ST-1009 FLEXIBLE COMPLETE BOARD.

Caution
Danger of explosion if battery is incorrectly replaced.
Replace only with the same or equivalent type.
Dispose of used batteries according to the instructions.

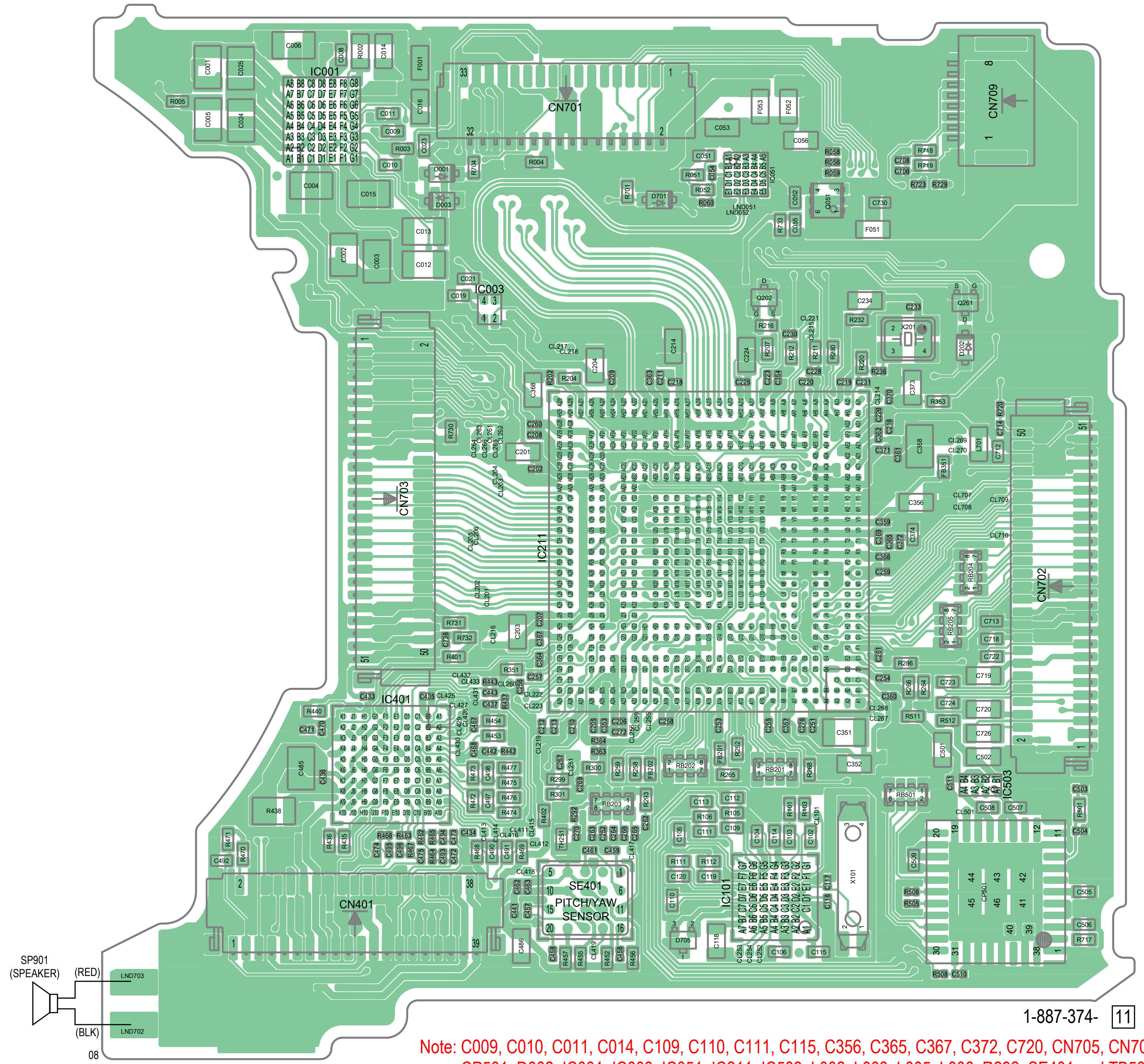
注意
電池の交換は，正しく行わないと破裂する恐れがあります。
電池を交換する場合には必ず同じ型名の電池又は同等品と交換してください。
使用済み電池は，取扱指示に従って処分してください。

: Uses unleaded solder.

SY-1015 BOARD (SIDE A)



SY-1015 BOARD (SIDE B)



Note: C009, C010, C011, C014, C109, C110, C111, C115, C356, C365, C367, C372, C720, CN705, CN706, CP501, D002, IC001, IC003, IC051, IC211, IC503, L002, L003, L005, L006, R292, SE401 and TB501 are not supplied, but they are included in SY-1015 COMPLETE BOARD (SERVICE).

: Uses unleaded solder.